# **Single 2-Input NAND Gate**

The MC74HC1G00 is a high speed CMOS 2–input NAND gate fabricated with silicon gate CMOS technology.

The internal circuit is composed of multiple stages, including a buffer output which provides high noise immunity and stable output.

- High Speed:  $t_{PD} = 7 \text{ ns} (Typ) \text{ at } V_{CC} = 5 \text{ V}$
- Low Power Dissipation:  $I_{CC} = 1 \ \mu A$  (Max) at  $T_A = 25^{\circ}C$
- High Noise Immunity
- Balanced Propagation Delays (t<sub>PLH</sub> = t<sub>PHL</sub>)
- Symmetrical Output Impedance (I<sub>OH</sub> = I<sub>OL</sub> = 2 mA)
- Chip Complexity: FETs = 40
- These Devices are Pb–Free and are RoHS Compliant
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

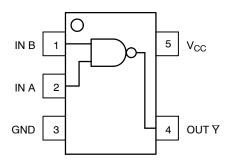




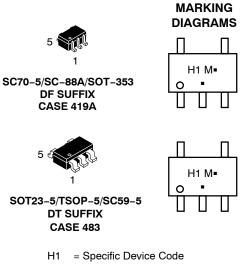


Figure 2. Logic Symbol



# **ON Semiconductor®**

http://onsemi.com



M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

PIN ASSIGNMENT								
1	IN B							
2	IN A							
3	GND							
4	Ουτ γ							
5	V <sub>CC</sub>							

### FUNCTION TABLE

Inp	Inputs					
А	В	Ÿ				
L	L	Н				
L	н	н				
Н	L	н				
Н	Н	L				

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

#### MAXIMUM RATINGS

Symbol		Value	Unit	
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +7.0	V
V <sub>IN</sub>	DC Input Voltage		$-0.5$ to $V_{CC}+0.5$	V
V <sub>OUT</sub>	DC Output Voltage		$-0.5$ to $V_{CC}+0.5$	V
I <sub>IK</sub>	DC Input Diode Current		±20	mA
I <sub>OK</sub>	DC Output Diode Current		±20	mA
I <sub>OUT</sub>	DC Output Sink Current		±12.5	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin		±25	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case	e for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias		+150	°C
$\theta_{JA}$	Thermal Resistance	SC70–5/SC–88A (Note 1) TSOP–5	350 230	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 85°	C SC70–5/SC–88A TSOP–5	150 200	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	>2000 >200 N/A	V
I <sub>LATCHUP</sub>	Latchup Performance	Above V <sub>CC</sub> and Below GND at 125°C (Note 5)	±500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace with no air flow.

2. Tested to EIA/JESD22-A114-A.

3. Tested to EIA/JESD22-A115-A.

4. Tested to JESD22-C101-A.

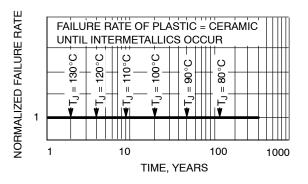
5. Tested to EIA/JESD78.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	DC Supply Voltage	2.0	6.0	V
V <sub>IN</sub>	DC Input Voltage	0.0	V <sub>CC</sub>	V
V <sub>OUT</sub>	DC Output Voltage	0.0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature Range	-55	+ 125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time $V_{CC} = 2.0 \ V_{CC} = 3.0 \ V_{CC} = 4.5 \ V_{CC} = 6.0 \ V_{CC} = $	/ 0 / 0 / 0 / 0	1000 600 500 400	ns

#### DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0





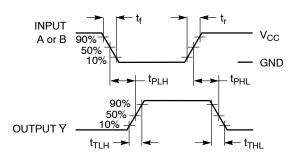
### DC ELECTRICAL CHARACTERISTICS

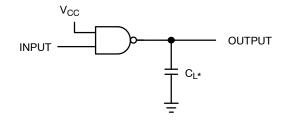
			V <sub>CC</sub>	٦	Γ <sub>A</sub> = 25°0	C	T <sub>A</sub> ≤	85°C	-55°C ≤ 1	Γ <sub>A</sub> ≤ 125°C	
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V <sub>IH</sub>	Minimum High-Level Input Voltage		2.0 3.0 4.5 6.0	1.5 2.1 3.15 4.20			1.5 2.1 3.15 4.20		1.5 2.1 3.15 4.20		V
V <sub>IL</sub>	Maximum Low-Level Input Voltage		2.0 3.0 4.5 6.0			0.5 0.9 1.35 1.80		0.5 0.9 1.35 1.80		0.5 0.9 1.35 1.80	V
V <sub>OH</sub>			2.0 3.0 4.5 6.0	1.9 2.9 4.4 5.9	2.0 3.0 4.5 6.0		1.9 2.9 4.4 5.9		1.9 2.9 4.4 5.9		V
			4.5 6.0	4.18 5.68	4.31 5.80		4.13 5.63		4.08 5.58		
V <sub>OL</sub>	$\label{eq:linear} \begin{array}{l} \mbox{Maximum Low-Level} \\ \mbox{Output Voltage} \\ \mbox{V}_{IN} = \mbox{V}_{IH} \mbox{ or } \mbox{V}_{IL} \end{array}$		2.0 3.0 4.5 6.0		0.0 0.0 0.0 0.0	0.1 0.1 0.1 0.1		0.1 0.1 0.1 0.1		0.1 0.1 0.1 0.1	V
			4.5 6.0		0.17 0.18	0.26 0.26		0.33 0.33		0.40 0.40	
I <sub>IN</sub>	Maximum Input Leakage Current	$V_{IN} = 6.0 \text{ V or GND}$	6.0			±0.1		±1.0		±1.0	μA
I <sub>CC</sub>	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	6.0			1.0		10		40	μΑ

### **AC ELECTRICAL CHARACTERISTICS** (Input $t_r = t_f = 6.0$ ns)

				Т	A = 25°0	2	T <sub>A</sub> ≤	85°C	-55°C ≤ 1	A ≤ 125°C	
Symbol	Parameter	Test Con	ditions	Min	Тур	Max	Min	Max	Min	Мах	Unit
t <sub>PLH</sub> ,	Maximum	V <sub>CC</sub> = 5.0 V	C <sub>L</sub> = 15 pF		3.5	15		20		25	ns
t <sub>PHL</sub>	Propagation Delay, Input A or B to ₹	$V_{CC} = 2.0 V \\ V_{CC} = 3.0 V \\ V_{CC} = 4.5 V \\ V_{CC} = 6.0 V$	C <sub>L</sub> = 50 pF		19 10.5 7.5 6.5	100 27 20 17		125 35 25 21		155 90 35 26	
t <sub>TLH</sub> ,	Output Transition	V <sub>CC</sub> = 5.0 V	C <sub>L</sub> = 15 pF		3	10		15		20	ns
t <sub>THL</sub>	Time	$V_{CC} = 2.0 V \\ V_{CC} = 3.0 V \\ V_{CC} = 4.5 V \\ V_{CC} = 6.0 V$	C <sub>L</sub> = 50 pF		25 16 11 9	125 35 25 21		155 45 31 26		200 60 38 32	
C <sub>IN</sub>	Maximum Input Capacitance				5	10		10		10	pF
							Туріс	al @ 25°	°C, V <sub>CC</sub> = 5.0	v	
C <sub>PD</sub>	Power Dissipation Ca	pacitance (Note	6)					1	10		pF

6.  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:  $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$ .  $C_{PD}$  is used to determine the no-load dynamic power consumption;  $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$ .





\*Includes all probe and jig capacitance. A 1-MHz square input wave is recommended for propagation delay tests.



# Figure 4. Switching Waveforms

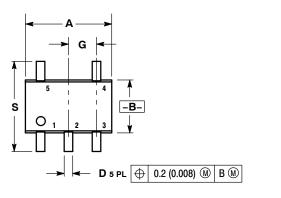
			Device Nom	enclature				
Device Order Number	Logic Circuit Indicator	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape and Reel Suffix	Package Type	Tape and Reel Size <sup>†</sup>
MC74HC1G00DFT1G	MC	74	HC1G	00	DF	T1	SC70-5/SC-88A/ SOT-353	178 mm (7 in) 3000 Unit
NLV74HC1G00DFT1G*	1						(Pb–Free)	3000 0111
MC74HC1G00DFT2G	MC	74	HC1G	00	DF	T2	SC70-5/SC-88A/ SOT-353 (Pb-Free)	178 mm (7 in) 3000 Unit
MC74HC1G00DTT1G	MC	74	HC1G	00	DT	T1	SOT23-5/TSOP-5/ SC59-5 (Pb-Free)	178 mm (7 in) 3000 Unit

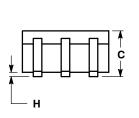
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. \*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP

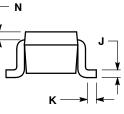
Capable.

### PACKAGE DIMENSIONS

SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE L



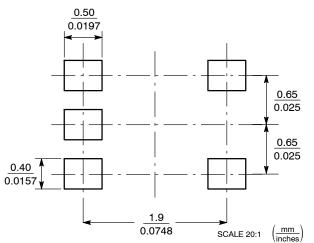




- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02. 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

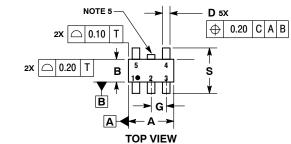
	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	0.026 BSC		BSC
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
Κ	0.004	0.012	0.10	0.30
Ν	0.008	REF	0.20	REF
S	0.079	0.087	2.00	2.20

SOLDER FOOTPRINT



#### PACKAGE DIMENSIONS

TSOP-5 CASE 483-02 **ISSUE K** 



SIDE VIEW

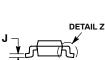
SEATING

C PLANE

□ 0.05







END VIEW

MILLIMETERS MIN MAX DIN 3.00 BSC А 1.50 BSC в 0.90 1.10 0.50 С D 0.25 G 0.95 BSC Н 0.01 0.10 J 0.10 0.26 Κ 0.20 0.60 Μ 0 10 S 2.50 3.00

FROM BODY

DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH

THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

MINIMUM THICKNESS OF BASE MAI EHIAL. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION A. OPTIONAL CONSTRUCTION: AN ADDITIONAL DIMMEDI FAD DI ALLOWED IN THUS LOCATION

TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2

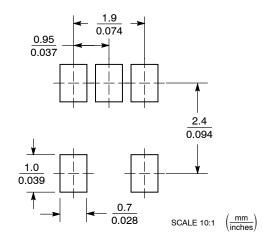
NOTES:

2

3

5

**SOLDERING FOOTPRINT\*** 



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and 💷 are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. Al listing of SCILLC's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without imitation special, consequential or incidental damages. Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typical" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

#### PUBLICATION ORDERING INFORMATION

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support:

ON Semiconductor Website: www.onsemi.com

For additional information, please contact your local

Order Literature: http://www.onsemi.com/orderlit

Sales Representative

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81-3-5817-1050

# **Mouser Electronics**

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

ON Semiconductor: MC74HC1G00DFT1G MC74HC1G00DFT2G MC74HC1G00DTT1G